

Abstract

Method for transporting, chemical-mechanical polishing and drying of workpieces, in particular silicon wafers in a sealed clean room with the following steps:

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the workpieces are removed by at least one transfer device from a loading and unloading station and transferred onto an intermediate station

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the workpieces are received by at least one polishing head of a polishing device of the intermediate station, transported to a polishing plate of the polishing device and held under rotation of the polishing head against the rotating polishing plate

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after polishing, the workpieces are transported back by the polishing head to the intermediate station, released from the polishing head and cleaned and/or chemically treated in the intermediate station

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the cleaned and/or chemically treated workpieces are transported from the intermediate station optionally to a second polishing device or to a washing or drying device and washed and dried therein

the washed and dried workpieces are transported back by the transfer device to the loading and unloading station

the polishing head is cleaned before each workpiece is received.